

# AMD Delivers the World's First and Only APU for Embedded Systems

The Low-Power AMD Embedded G-Series Platform Uniquely Meets Today's Market Trends, Provides Embedded Market a Brand New x86 Core Integrated With GPU and DirectX(R) 11 Support

SUNNYVALE, CA -- (MARKET WIRE) -- 01/19/11 -- AMD (NYSE: AMD) today announced immediate availability of the new <u>AMD Embedded G-Series processor</u>, the world's first and only Accelerated Processing Unit (APU) for embedded systems. The AMD Embedded G-Series, based on AMD Fusion technology, delivers a complete, full-featured embedded platform and incorporates the new low-power, x86 CPU based on the "Bobcat" core with a world-class DirectX® 11-capable GPU and parallel processing engine on a single piece of silicon.

- This new class of accelerated processor combines more compute capabilities on a single die than any processor in the history of computing and represents opportunity for major advancements in embedded systems.
- No solution with this level of advanced computing is available for the embedded market today.
- Numerous embedded systems based on the AMD Embedded G-Series are available today or expected to launch in the coming weeks from companies including Advansus, Compulab, Congatec, Fujitsu, Haier, iEi, Kontron, Mitec, Quixant, Sintrones, Starnet, WebDT, Wyse, and many others.
- Expected products include graphics-intensive solutions like digital signage, internetready set top boxes, mobile and desktop thin clients, casino gaming machines, pointof-sale kiosks, and small form factor PCs, as well as numerous single board computers (SBCs).
- Shane Rau, research director of Computing and Storage Semiconductors at IDC, expects shipments of processors for embedded systems to increase at a double digit rate each year for the next five years.
- This brand new platform continues AMD's mission to lower power, shrink physical component area, and reduce the costs of designing and producing x86 embedded systems.

"AMD's commitment is to ensure the game-changing technologies we develop for consumers and the enterprise are also available for the vast and growing embedded market," said Patrick Patla, corporate vice president and general manager, Server and Embedded Division, AMD. "Today, we have a record number of embedded launch partners. They are using the unique advancements of the AMD Embedded G-Series APU to develop a brand new generation of highly differentiated, energy-efficient, small form-factor embedded systems that can deliver the vivid visual experience expected in our always-connected world."

AMD has assessed many of the trends shaping today's embedded market, including the ever-pressing need for power efficiency and a small footprint, along with high CPU performance, full feature sets, and a strong graphics solution. The embedded market is one where differentiation can be critical to the long-term success of a design. The AMD Embedded G-Series APU provides a small, open and flexible platform where system designers can be creative yet still meet strict requirements around development cost.

# Design and Development Support

- The open development ecosystem for the AMD Embedded G-Series platform includes multiple BIOS options, support for various Microsoft Windows<sup>®</sup>, Linux, and real-time operating systems, the integrated OpenCL™ programming environment, and sourcelevel debug tools.
- AMD provides a dedicated design support team to help customers create distinctive new products and bring them to market quickly.
- Online resources include an <u>embedded developer portal</u>, <u>AMD embedded product</u> <u>selection guide</u> and customer-submitted details on <u>available boards and complete</u> <u>systems</u>.

# AMD Embedded G-Series APU Specifications

- 1 or 2 x86 "Bobcat" CPU cores with 1MB L2 cache, 64-bit Floating Point Unit
- Up to 1.6GHz
- 9W and 18W TDP
- Array of SIMD Engines
  - DirectX<sup>®</sup> 11 capable graphics
  - Industry-leading 3D and graphics processing
- 3rd Generation Unified Video Decoder
- Power management features, including C6 and power gating
- DDR3 800-1066 memory with support for 64 bit channel and 2 DIMMs
- Ball Grid Array (BGA) package
- 890mm(2) physical footprint, including the AMD Fusion I/O Controller Hub

### Supporting Resources

- AMD@Work/Embedded blog
- Fujitsu guest blog post
- Kontron guest blog post
- AMD Embedded G-Series Press Kit
- AMD Embedded G-Series Press Presentation
- www.amd.com/embedded

### About AMD

AMD (NYSE: AMD) is a semiconductor design innovator leading the next era of vivid digital experiences with its ground-breaking AMD Fusion Accelerated Processing Units (APUs). AMD's graphics and computing technologies power a variety of devices including PCs, game consoles and the powerful computers that drive the Internet and businesses. For more information, visit <a href="http://www.amd.com">http://www.amd.com</a>.

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This release contains forward-looking statements concerning among other things the timing of the planned introduction of our customers' products based on our products, which are made pursuant to the safe harbor provisions of the Private Securities Litigation Reform Act of 1995. Forward-looking statements are commonly identified by words such as "would," "may," "expects," "believes," "plans," "intends," "projects," and other terms with similar meaning. Investors are cautioned that the forward-looking statements in this release are based on current beliefs, assumptions and expectations, speak only as of the date of these presentations and involve risks and uncertainties that could cause actual results to differ materially from current expectations. The material factors that could cause actual results to differ materially from current expectations include, without limitation, the following: the effect of political or economic instability internationally on sales or production; demand for computers and consumer electronics products and, in turn, demand for AMD's products will be lower than currently expected; customers will stop buying AMD's products or materially reduce their demand for its products; third parties will not develop or improve software that is optimized for AMD products; there will be unexpected variations in market growth and demand for AMD's products and technologies in light of the product mix that it may have available at any particular time or a decline in demand; the possibility that Intel Corporation's pricing, marketing and rebating programs, product bundling, standard setting, new product introductions or other activities targeting AMD's business will prevent attainment of AMD's current plans; AMD will be unable to develop, launch and ramp new products and technologies in the volumes and mix required by the market; AMD's third party wafer foundries will be unable to manufacture its products on a timely basis with acceptable quality, at acceptable manufacturing yields and using competitive technologies; AMD's third party wafer foundries will be unable to transition to advanced manufacturing process technologies in a timely and effective way, consistent with AMD's planned expenditures; AMD will be unable to maintain the level of investment in research and development that is required to remain competitive; AMD will require additional funding and may not be able to raise funds on favorable terms or at all; any inability to obtain sufficient manufacturing capacity or components to meet demand for AMD's products or the under-utilization of GLOBALFOUNDRIES manufacturing facilities; or that GLOBALFOUNDRIES will be less successful than anticipated. Investors are urged to review in detail the risks and uncertainties in the company's Securities and Exchange Commission filings, including but not limited to the Quarterly Report on Form 10-Q for the quarter ended September 25, 2010.

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